

**REMARKS**

No claims have been amended, added or canceled. Accordingly, claims 3, 4, 7, 8, 11, 12 and 15-26 are currently pending in the application.

**PRIORITY**

Applicants appreciate the Examiner's acknowledgement of the claim for priority and safe receipt of the certified priority document.

**INFORMATION DISCLOSURE STATEMENT**

On January 15, 2003, Applicants filed an Information Disclosure Statement. However, the Examiner has not returned an initialed PTO-1449 Form. Accordingly, it is requested that the Examiner initial and return a copy of the attached PTO-1449 Form to indicate that the reference has been considered.

**35 U.S.C. §102**

Claims 3, 4, 7, 8, 11, 12, 15 and 16 stand rejected under 35 U.S.C. §102 as being anticipated by Hase et al. Claims 17-26 stand rejected under 35 U.S.C. §102 as being anticipated by Hase et al. These rejections are traversed as follows.

As stated in the previously filed response, according to the present invention, a part 35 of ground metal 19 on the surface of the second-layer dielectric substrate is removed without creating a hole or aperture through dielectric substrate 18 (see Figure 1 and page 11, lines 10-14, for example). In response, the Examiner states that the above-cited portion of the specification does not support Applicants' contention. Applicants disagree because the cited portion of the specification along with Figure 1 clearly indicate that no hole is formed through dielectric substrate 18. However, as further support, Applicants direct the Examiner's attention to page 12, lines 2-12, reproduced below:

In this embodiment, the first-layer dielectric substrate 1 and the second-layer dielectric substrate 18 continues between the conductor line 9 and the ground metal 29, and for the thickness between both, the thickness of the second-layer dielectric substrate 18 is added to that of the first-layer dielectric substrate 1. Therefore, the thickness between the conductor line 9 and the ground metal 29 can be thicker than the thickness of only the first-layer dielectric substrate 1 or the second-layer dielectric substrate 18 any transmission loss can be reduced. (Underlining added)

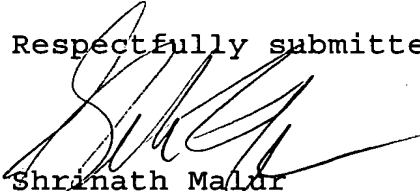
Therefore, the claimed structure and attending advantages are clearly contained in the above-cited passage from the specification. This structure and advantage is not disclosed or realized by the cited reference to Hase et al. Hase et al

clearly disclose that a hole is formed in the dielectric substrate, which results in bending of the portion of the substrate above the hole onto which a high-frequency circuit element is mounted. This changes the impedance of the high-frequency circuit and could create other problems such as a break in the circuit.

**CONCLUSION**

In view of the foregoing amendments and remarks, Applicants contend that the above-identified application is now in condition for allowance. Accordingly, reconsideration and reexamination are respectfully requested.

Respectfully submitted,

  
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